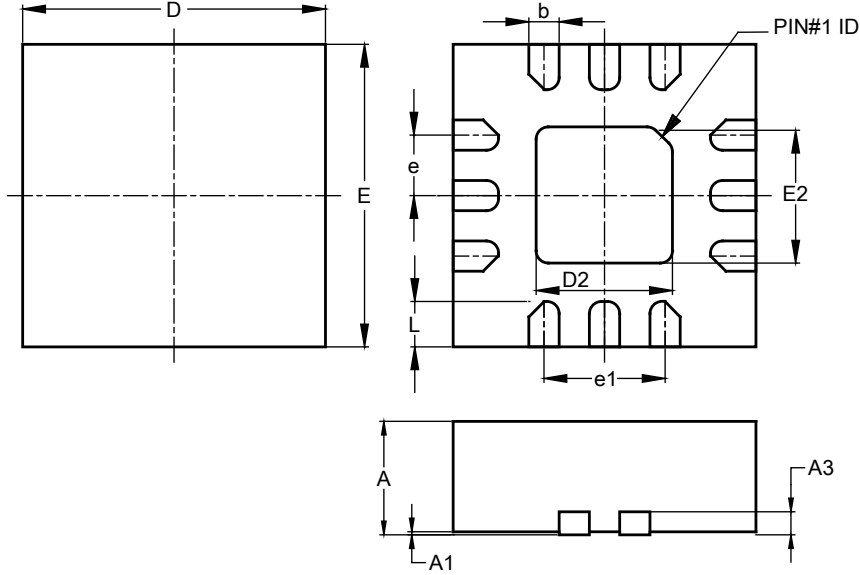


**Package Outline Dimensions**

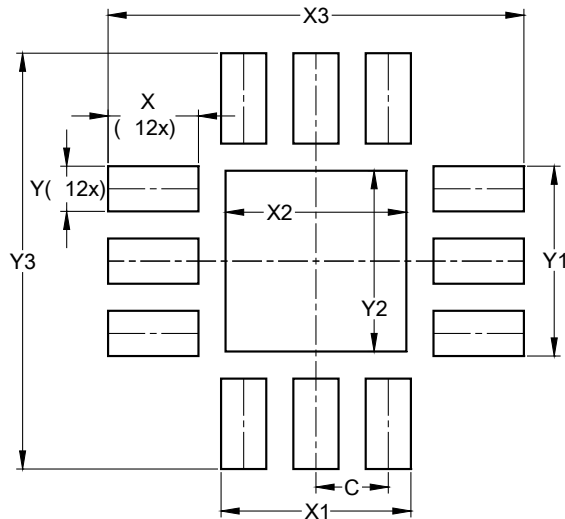
W-QFN2020-12 (Type US)



W-QFN2020-12 (Type US)			
Dim	Min	Max	Typ
A	0.700	0.800	0.750
A1	0.00	0.050	--
A3	0.203REF		
b	0.150	0.250	0.200
D	1.950	2.050	2.000
D2	0.850	0.950	0.900
E	1.950	2.050	2.000
E2	0.850	0.950	0.900
e	0.400 BSC		
e1	0.800 REF		
L	0.250	0.350	0.300
All Dimensions in mm			

**Suggested Pad Layout**

W-QFN2020-12 (Type US)



Dimensions	Value (in mm)
C	0.400
X	0.500
X1	1.050
X2	1.000
X3	2.300
Y	0.250
Y1	1.050
Y2	1.000
Y3	2.300

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.